

FDD5690

60V N-Channel PowerTrench® MOSFET

General Description

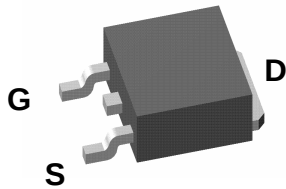
This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers.

These MOSFETs feature faster switching and lower gate charge than other MOSFETs with comparable $R_{DS(ON)}$ specifications.

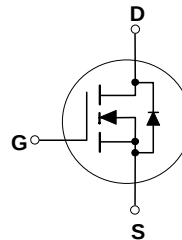
The result is a MOSFET that is easy and safer to drive (even at very high frequencies), and DC/DC power supply designs with higher overall efficiency.

Features

- 30 A, 60 V. $R_{DS(ON)} = 0.027\Omega @ V_{GS} = 10\text{ V}$
 $R_{DS(ON)} = 0.032\Omega @ V_{GS} = 6\text{ V}$.
- Low gate charge (23nC typical).
- Fast switching speed.
- High performance trench technology for extremely low $R_{DS(ON)}$.



TO-252



Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DSS}	Drain-Source Voltage	60	V
V_{GSS}	Gate-Source Voltage	± 20	V
I_D	Maximum Drain Current -Continuous (Note 1)	30	A
	(Note 1a)	9	
	Maximum Drain Current -Pulsed	100	
P_D	Maximum Power Dissipation @ $T_C = 25^\circ\text{C}$ (Note 1)	50	W
	$T_A = 25^\circ\text{C}$ (Note 1a)	3.2	
	$T_A = 25^\circ\text{C}$ (Note 1b)	1.3	
T_J, T_{stg}	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ\text{C}$

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction-to- Case (Note 1)	2.5	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to- Ambient (Note 1a)	40	$^\circ\text{C/W}$
		96	$^\circ\text{C/W}$

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
FDD5690	FDD5690	13"	16mm	2500

Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
W_{DSS}	Single Pulse Drain-Source Avalanche Energy	$V_{DD} = 30\text{ V}$, $I_D = 30\text{ A}$			90	mJ
I_{AR}	Maximum Drain-Source Avalanche Current				30	A
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}$, $I_D = 250\text{ }\mu\text{A}$	60			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$, Referenced to 25°C		57		mV/ $^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 48\text{ V}$, $V_{GS} = 0\text{ V}$			1	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 20\text{ V}$, $V_{DS} = 0\text{ V}$			100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -20\text{ V}$, $V_{DS} = 0\text{ V}$			-100	nA

On Characteristics (Note 2)

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$	2	2.5	4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$, Referenced to 25°C		-6		mV/ $^\circ\text{C}$
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10\text{ V}$, $I_D = 9\text{ A}$ $V_{GS} = 10\text{ V}$, $I_D = 9\text{ A}$, $T_J = 125^\circ\text{C}$ $V_{GS} = 6\text{ V}$, $I_D = 8\text{ A}$		0.023 0.032 0.026	0.027 0.048 0.032	Ω
$I_{D(on)}$	On-State Drain Current	$V_{GS} = 10\text{ V}$, $V_{DS} = 5\text{ V}$	25			A
g_{FS}	Forward Transconductance	$V_{DS} = 5\text{ V}$, $I_D = 9\text{ A}$		24		S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 25\text{ V}$, $V_{GS} = 0\text{ V}$ $f = 1.0\text{ MHz}$		1110		pF
C_{oss}	Output Capacitance			150		pF
C_{rss}	Reverse Transfer Capacitance			75		pF

Switching Characteristics (Note 2)

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 30\text{ V}$, $I_D = 1\text{ A}$ $V_{GS} = 10\text{ V}$, $R_{GEN} = 6\text{ }\Omega$		10	18	ns
t_r	Turn-On Rise Time			9	18	ns
$t_{d(off)}$	Turn-Off Delay Time			24	39	ns
t_f	Turn-Off Fall Time			10	18	ns
Q_g	Total Gate Charge	$V_{DS} = 30\text{ V}$, $I_D = 9\text{ A}$ $V_{GS} = 10\text{ V}$,		23	32	nC
Q_{gs}	Gate-Source Charge			4		nC
Q_{gd}	Gate-Drain Charge			6.8		nC

Drain-Source Diode Characteristics and Maximum Ratings

I_S	Maximum Continuous Drain-Source Diode Forward Current				2.3	A
V_{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{ V}$, $I_S = 2.3\text{ A}$ (Note 2)		0.75	1.2	V

Notes:

1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the drain tab.

$R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



■ a) $R_{\theta JA} = 40^\circ\text{C/W}$ when mounted
■ on a 1 in^2 pad of 2oz copper.



■ b) $R_{\theta JA} = 96^\circ\text{C/W}$ on a minimum
■ mounting pad.

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width $\leq 300\text{ }\mu\text{s}$, Duty Cycle $\leq 2.0\%$

Typical Characteristics

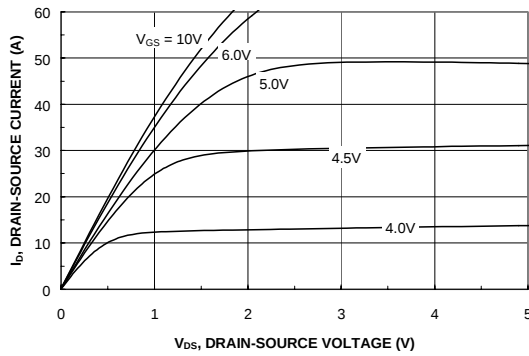


Figure 1. On-Region Characteristics.

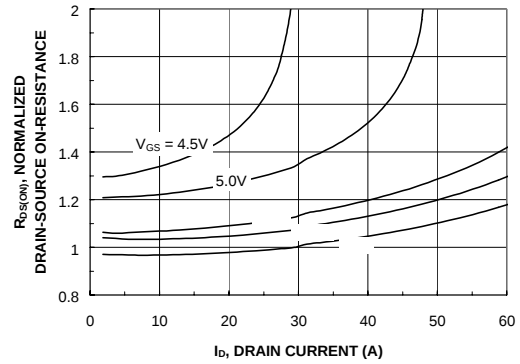


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

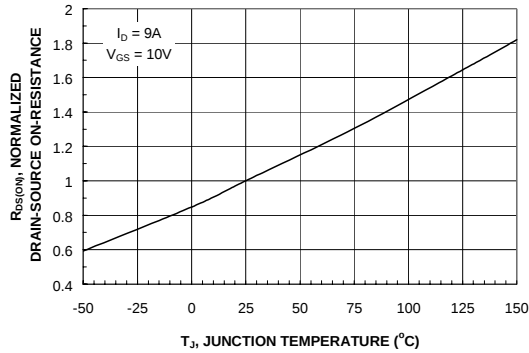


Figure 3. On-Resistance Variation with Temperature.

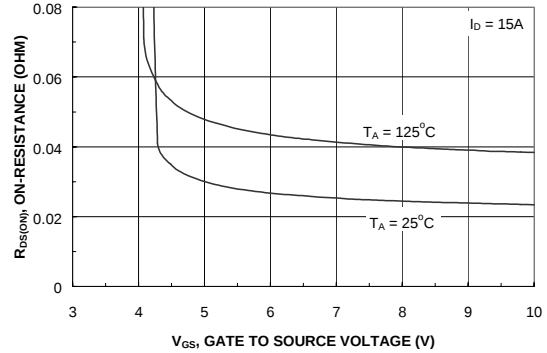


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

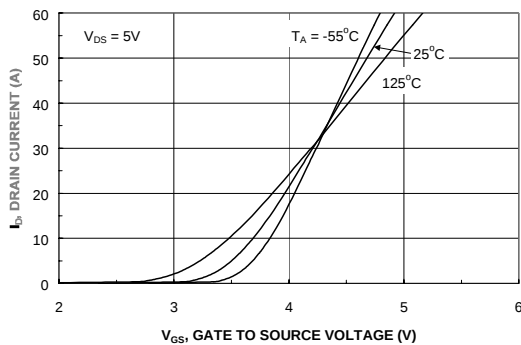


Figure 5. Transfer Characteristics.

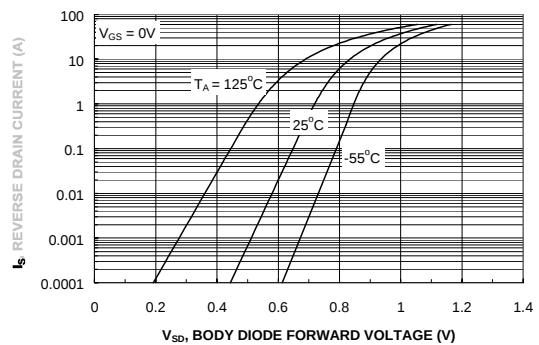


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics (continued)

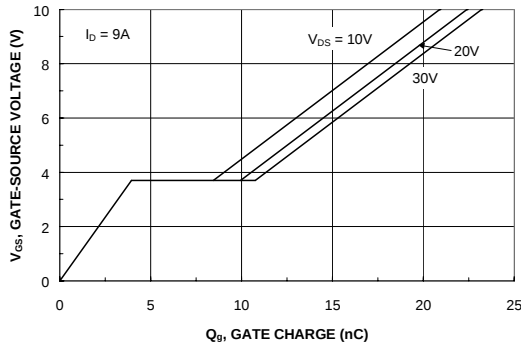


Figure 7. Gate-Charge Characteristics.

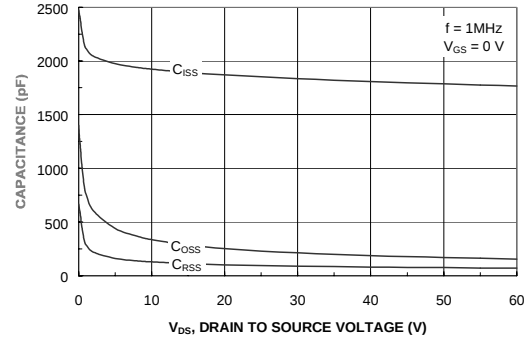


Figure 8. Capacitance Characteristics.

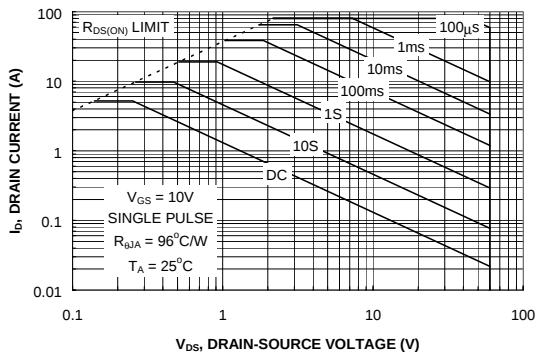


Figure 9. Maximum Safe Operating Area.

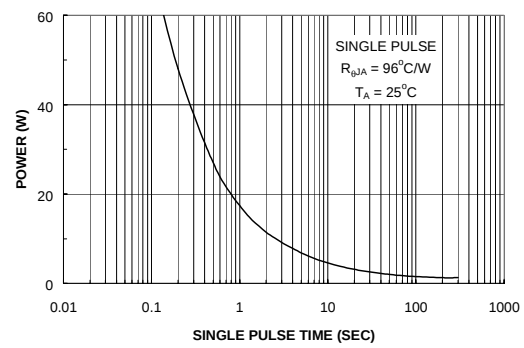


Figure 10. Single Pulse Maximum Power Dissipation.

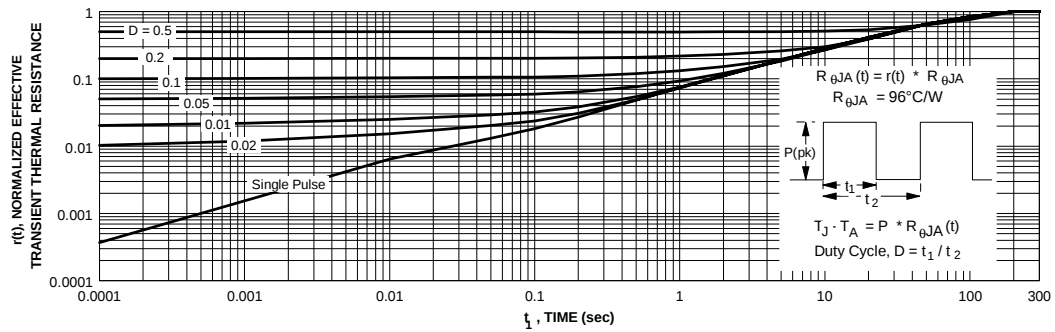


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1b.
Transient thermal response will change depending on the circuit board design.

TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

ACE ^{Ex} TM	FACT TM	ImpliedDisconnect TM	PACMAN TM	SPM TM
ActiveArray TM	FACT Quiet Series TM	ISOPLANAR TM	POP TM	Stealth TM
Bottomless TM	FAST [®]	LittleFET TM	Power247 TM	SuperSOT TM -3
CoolFET TM	FAST ^r TM	MicroFET TM	PowerTrench [®]	SuperSOT TM -6
CROSSVOLT TM	FRFET TM	MicroPak TM	QFET TM	SuperSOT TM -8
DOME TM	GlobalOptoisolator TM	MICROWIRE TM	QS TM	SyncFET TM
EcoSPARK TM	GTO TM	MSX TM	QT Optoelectronics TM	TinyLogic TM
E ² CMOS TM	HiSeC TM	MSXPro TM	Quiet Series TM	TruTranslation TM
EnSigna TM	I ² C TM	OCX TM	RapidConfigure TM	UHC TM
Across the board. Around the world. TM		OCXPro TM	RapidConnect TM	UltraFET [®]
The Power Franchise TM		OPTOLOGIC [®]	SILENT SWITCHER [®]	VCX TM
Programmable Active Droop TM		OPTOPLANAR TM	SMART START TM	

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.